



# SOT763-1

plastic dual in-line compatible thermal enhanced very thin quad flat package; no leads; 16 terminals; body 2.5 x 3.5 x 0.85 mm

30 May 2016

Package information

## 1. Package summary

<b>Terminal position code</b>	Q (quad)
<b>Package type descriptive code</b>	DHVQFN16
<b>Package type industry code</b>	DHVQFN16
<b>Package style descriptive code</b>	DHVQFN (DIL-compatible thermal enhanced very thin quad flatpack; no leads)
<b>Package style suffix code</b>	NA (not applicable)
<b>Package body material type</b>	P (plastic)
<b>IEC package outline code</b>	---
<b>JEDEC package outline code</b>	MO-241
<b>JEITA package outline code</b>	---
<b>Mounting method type</b>	S (surface mount)
<b>Issue date</b>	27-1-2003

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	3.4	-	3.5	3.6	mm
E	package width	2.4	-	2.5	2.6	mm
A	seated height	-	-	0.85	1	mm
A <sub>2</sub>	package height	-	-	0.85	-	mm
e	nominal pitch	-	-	-	-	
n <sub>2</sub>	actual quantity of termination	-	-	16	-	

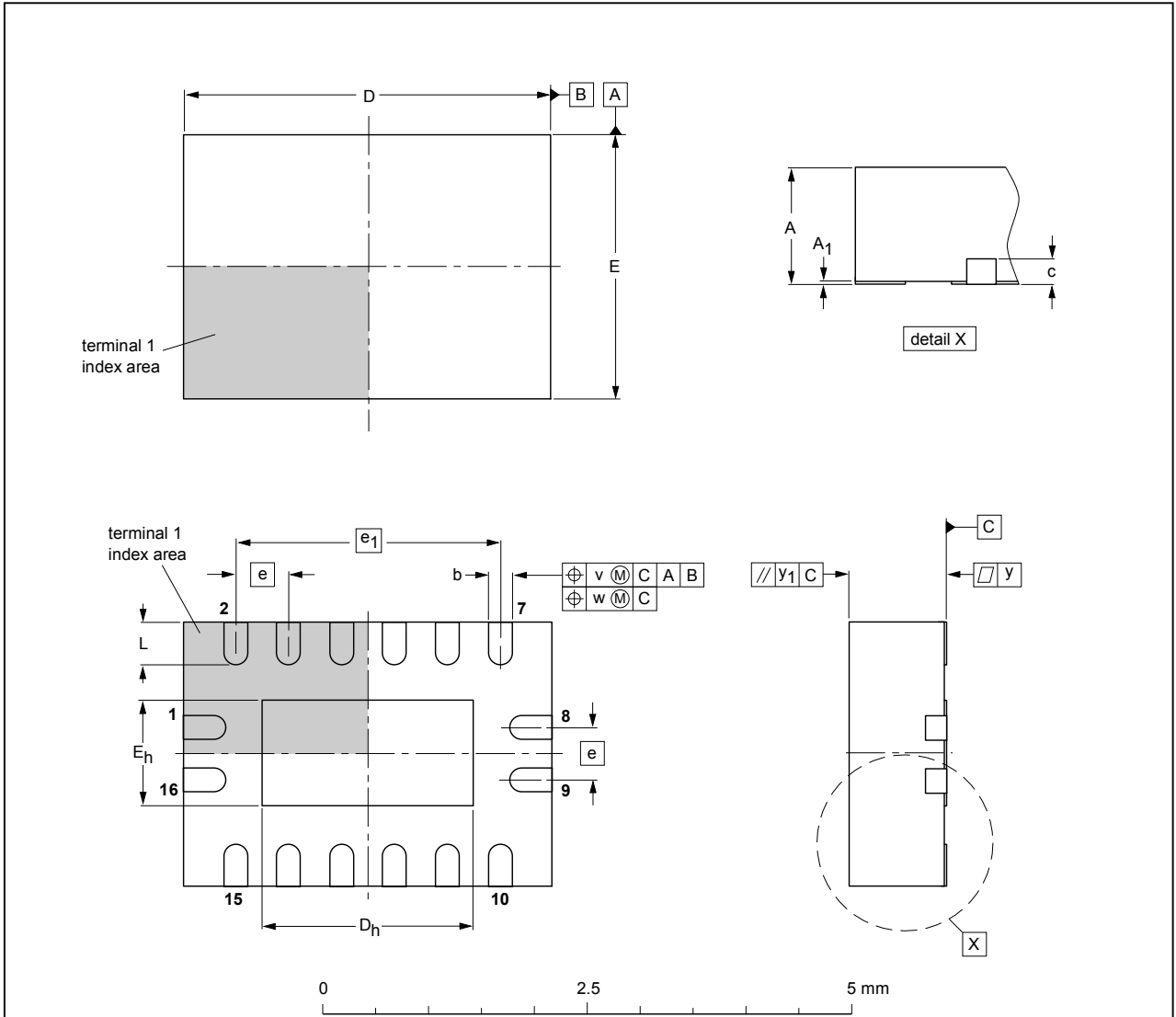


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## 2. Package outline

DHVQFN16: plastic dual in-line compatible thermal enhanced very thin quad flat package; no leads; 16 terminals; body 2.5 x 3.5 x 0.85 mm

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**DIMENSIONS** (mm are the original dimensions)

UNIT	A <sup>(1)</sup> max.	A <sub>1</sub>	b	c	D <sup>(1)</sup>	D <sub>h</sub>	E <sup>(1)</sup>	E <sub>h</sub>	e	e <sub>1</sub>	L	v	w	y	y <sub>1</sub>
mm	1	0.05 0.00	0.30 0.18	0.2	3.6 3.4	2.15 1.85	2.6 2.4	1.15 0.85	0.5	2.5	0.5 0.3	0.1	0.05	0.05	0.1

**Note**

1. Plastic or metal protrusions of 0.075 mm maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT763-1	---	MO-241	---			02-10-17 03-01-27

Fig. 1. Package outline DHVQFN16 (SOT763-1)

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### 3. Soldering

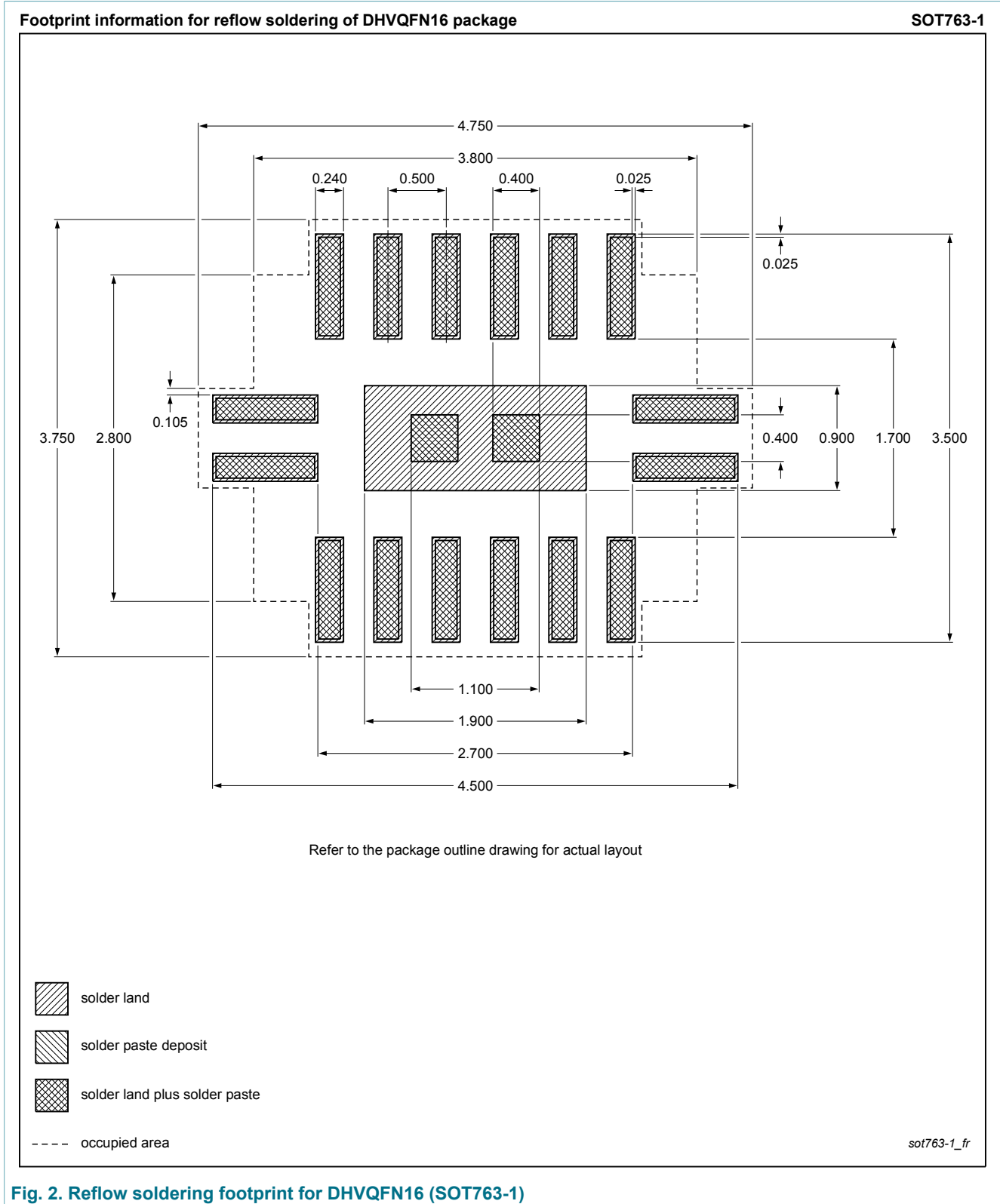


Fig. 2. Reflow soldering footprint for DHVQFN16 (SOT763-1)

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## 4. Legal information

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